

100V N-Channel Enhancement Mode MOSFET

Voltage 100 V Current 40 A

Features

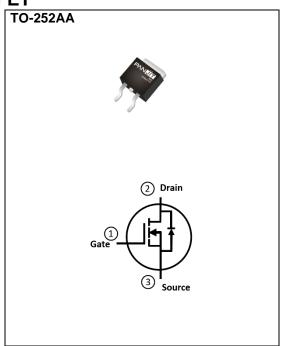
- RDS(ON), VGS@10V, ID@20A<18m Ω
- RDS(ON), VGS@4.5V, ID@10A<26m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: TO-252AA Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.3217 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V_{DS}	100	V	
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C		40		
	T _C =100°C	l _D	28	Α	
Pulsed Drain Current ^(Note 1)	Tc=25°C	I _{DM}	145		
Power Dissipation	Tc=25°C	D-	58	W	
	T _C =100°C	Po	29		
Continuous Drain Current(Note 4)	T _A =25°C	- I _D	9	А	
	T _A =70°C		7.6		
Power Dissipation	T _A =25°C	PD	3	W	
	T _A =70°C		2.1		
Single Pulse Avalanche Current(Note 5)		las	17	Α	
Single Pulse Avalanche Energy ^(Note 5)		Eas	32	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	R _{θJC}	2.6	°C/W	
	Junction to Ambient	R _{θJA}	50		



Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static							
Drain-Source Breakdown Voltage	BV _{DSS} V _{GS} =0V, I _D =250uA		100	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA 1		2	3		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	14.1	18	0	
		V _{GS} =4.5V, I _D =10A	- 20.4 2		26	mΩ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Qg	V _{DS} =50V, I _D =20A,	-	23	-	nC	
Gate-Source Charge	Qgs		-	5.1	-		
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	6.1	-		
Input Capacitance	Ciss	., -0.//	-	1009	-	pF	
Output Capacitance	Coss	V _{DS} =50V, V _{GS} =0V,	-	173	-		
Reverse Transfer Capacitance	Crss	f=1MHz	-	23	-		
Gate resistance	Rg	f=1MHz	-	1	-	Ω	
Turn-On Delay Time	td _(on)	.,,	-	7.1	-	ns	
Turn-On Rise Time	tr	V _{DS} =50V, I _D =20A,	-	14	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$	-	20	-		
Turn-Off Fall Time	tf	(Note 2)	-	16	-		
Drain-Source Diode							
Diode Forward Current	Is	T 05°0	-	-	40		
Pulsed Diode Forward Current	I _{SM}	T _C =25°C	-	-	145	А	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V	-	0.85	1.3	V	
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	38	-	ns	
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	28	-	nC	

NOTES:

- 1. Pulse width<100us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{0JC}=2.6°C/W.
- 4. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. E_{AS} is calculated based on the condition of L=1mH, I_{AS}=8A, V_{DD}=30V, V_{GS}=10V. 100% test at L=0.1mH, I_{AS}=17A in production.
- 6. Guaranteed by design, not subject to production testing.



TYPICAL CHARACTERISTIC CURVES

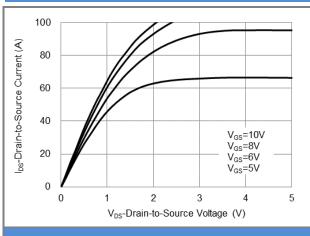


Fig.1 On-Region Characteristics

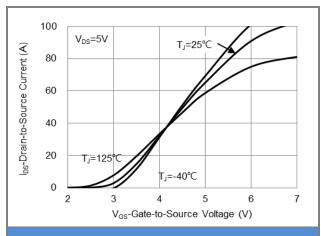


Fig.2 Transfer Characteristics

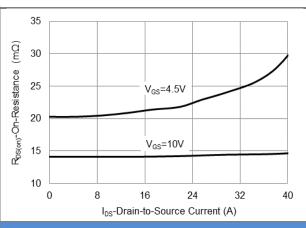


Fig.3 On-Resistance vs. Drain Current

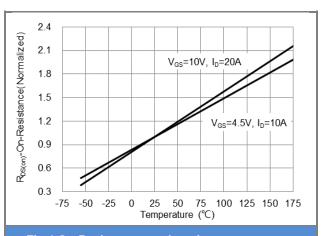


Fig.4 On-Resistance vs. Junction temperature

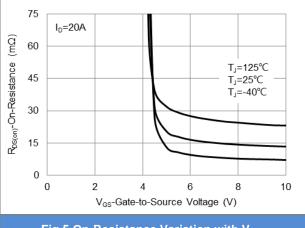
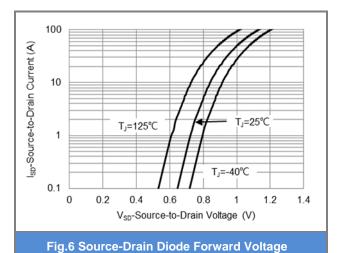


Fig.5 On-Resistance Variation with V_{GS}





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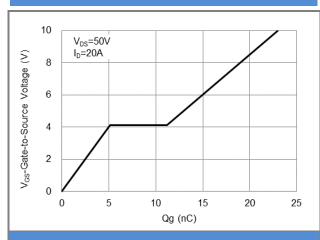


Fig.7 Gate-Charge Characteristics

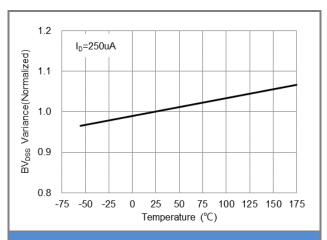


Fig.8 Breakdown Voltage Variation vs. Temperature

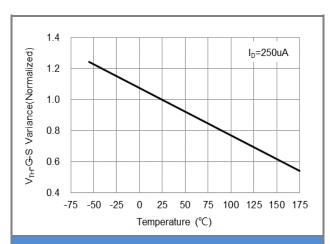


Fig.9 Threshold Voltage Variation with Temperature

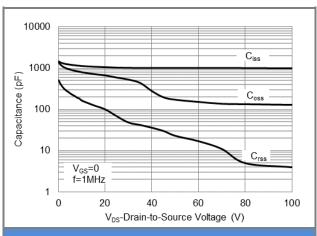
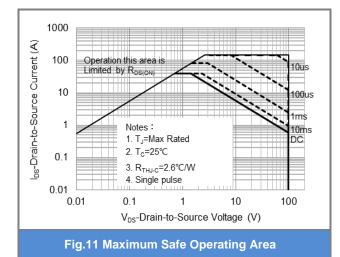


Fig.10 Capacitance vs. Drain-Source Voltage



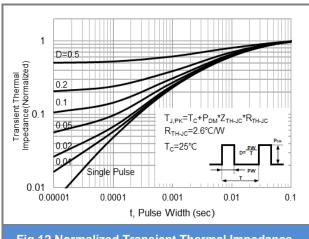


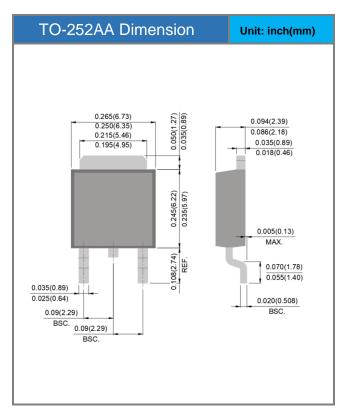
Fig.12 Normalized Transient Thermal Impedance

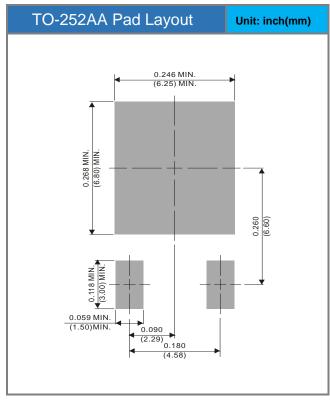


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJD50N10SA-AU	TO-252AA	3K pcs / 13" reel	50N10SA	

Packaging Information & Mounting Pad Layout







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